

# MR27V6454G

4M-Word × 16-Bit Page Mode **P2ROM**

## FEATURES

- 4,194,304-word × 16-bit configuration
- Page size of 8-word x 16-Bit
- 3.0 V to 3.6 V power supply
- Random Access time..... 100 ns MAX
- Page Access time ..... 30 ns MAX
- Operating current ..... 50 mA MAX (5MHz)
- Standby current ..... 10 µA MAX
- Input/Output TTL compatible
- Three-state output

## PACKAGES

- MR27V6454G-xxxTN  
48-pin plastic TSOP (TSOP I 48-P-1220-0.50-1K)

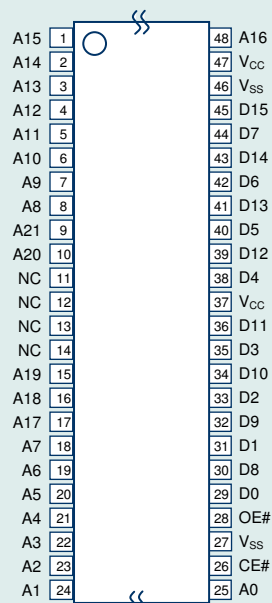
## P2ROM ADVANCED TECHNOLOGY

P2ROM stands for Production Programmed ROM. This exclusive LAPIS Semiconductor technology utilizes factory test equipment for programming the customers code into the P2ROM prior to final production testing.

Advancements in this technology allows production costs to be equivalent to MASKROM and has many advantages and added benefits over the other non-volatile technologies, which include the following;

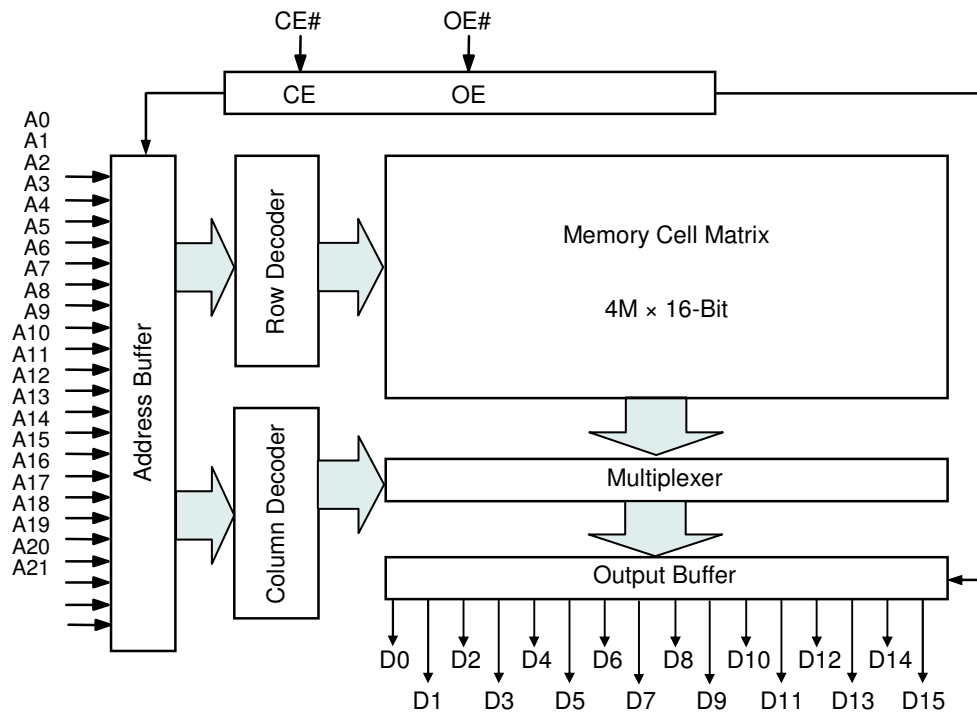
- **Short lead time**, since the P2ROM is programmed at the final stage of the production process, a large P2ROM inventory "bank system" of un-programmed packaged products are maintained to provide an aggressive lead-time and minimize liability as a custom product.
- **No mask charge**, since P2ROMs do not utilize a custom mask for storing customer code, no mask charges apply.
- **No additional programming charge**, unlike Flash and OTP that require additional programming and handling costs, the P2ROM already has the code loaded at the factory with minimal effect on the production throughput. The cost is included in the unit price.
- **Custom Marking is** available at no additional charge.
- **Pin Compatible with Mask ROM** and some FLASH products.

## PIN CONFIGURATION (TOP VIEW)



48TSOP(Type-I)

## BLOCK DIAGRAM



## PIN DESCRIPTIONS

Pin name	Functions
A0 to A21	Address inputs
D0 to D15	Data outputs
CE#	Chip enable input
OE#	Output enable input
V <sub>CC</sub>	Power supply voltage
V <sub>SS</sub>	Ground
NC	No connect

**FUNCTION TABLE**

Mode	CE#	OE#	V <sub>CC</sub>	D0 to D15
Read	L	L	3.3 V	Dout
Output disable	L	H		Hi-Z
Standby	H	*		Hi-Z

\*: Don't Care (H or L)

**ABSOLUTE MAXIMUM RATINGS**

Parameter	Symbol	Condition	Value	Unit
Operating temperature under bias	T <sub>a</sub>	—	0 to 70	°C
Storage temperature	T <sub>stg</sub>		-55 to 125	°C
Input voltage	V <sub>I</sub>	relative to V <sub>SS</sub>	-0.5 to V <sub>CC</sub> +0.5	V
Output voltage	V <sub>O</sub>		-0.5 to V <sub>CC</sub> +0.5	V
Power supply voltage	V <sub>CC</sub>		-0.5 to 5	V
Power dissipation per package	P <sub>D</sub>	T <sub>a</sub> = 25°C	1.0	W
Output short circuit current	I <sub>OS</sub>	—	10	mA

**RECOMMENDED OPERATING CONDITIONS**(T<sub>a</sub> = 0 to 70°C)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
V <sub>CC</sub> power supply voltage	V <sub>CC</sub>	V <sub>CC</sub> = 3.0 to 3.6 V	3.0	—	3.6	V
Input "H" level	V <sub>IH</sub>		2.2	—	V <sub>CC</sub> +0.5*	V
Input "L" level	V <sub>IL</sub>		-0.5**	—	0.6	V

Voltage is relative to V<sub>SS</sub>.\* : V<sub>CC</sub>+1.5V (Max.) when pulse width of overshoot is less than 10ns.

\*\* : -1.5V (Min.) when pulse width of undershoot is less than 10ns.

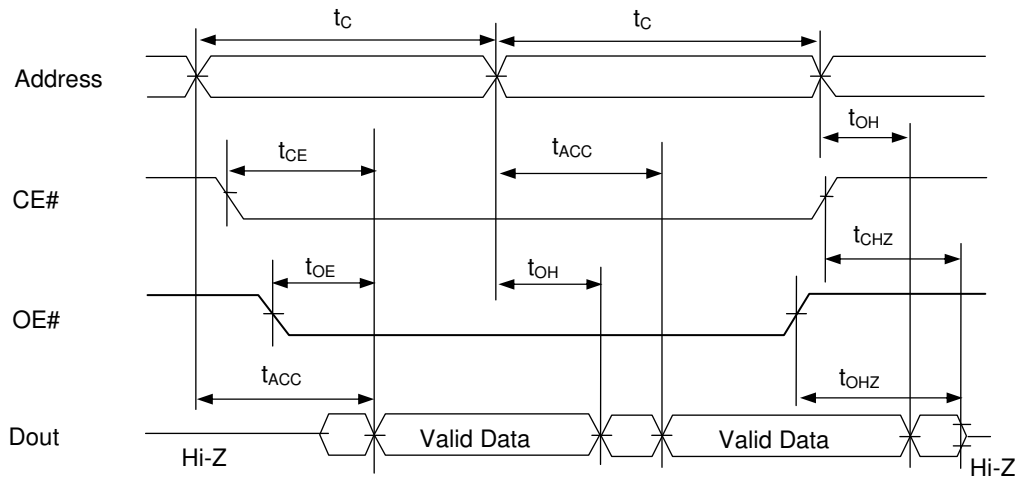
**PIN CAPACITANCE**(V<sub>CC</sub> = 3.3 V, T<sub>a</sub> = 25°C, f = 1 MHz)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Input	C <sub>IN1</sub>	V <sub>I</sub> = 0 V	—	—	8	pF
Output	C <sub>OUT</sub>	V <sub>O</sub> = 0 V	—	—	10	

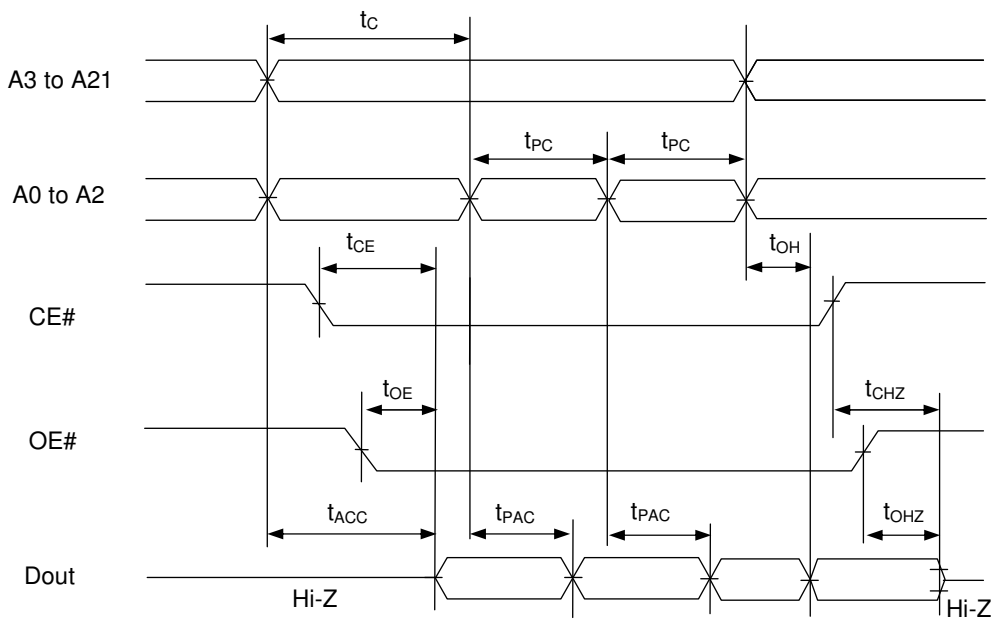


**TIMING CHART (READ CYCLE)**

**RANDOM ACCESS MODE READ CYCLE**

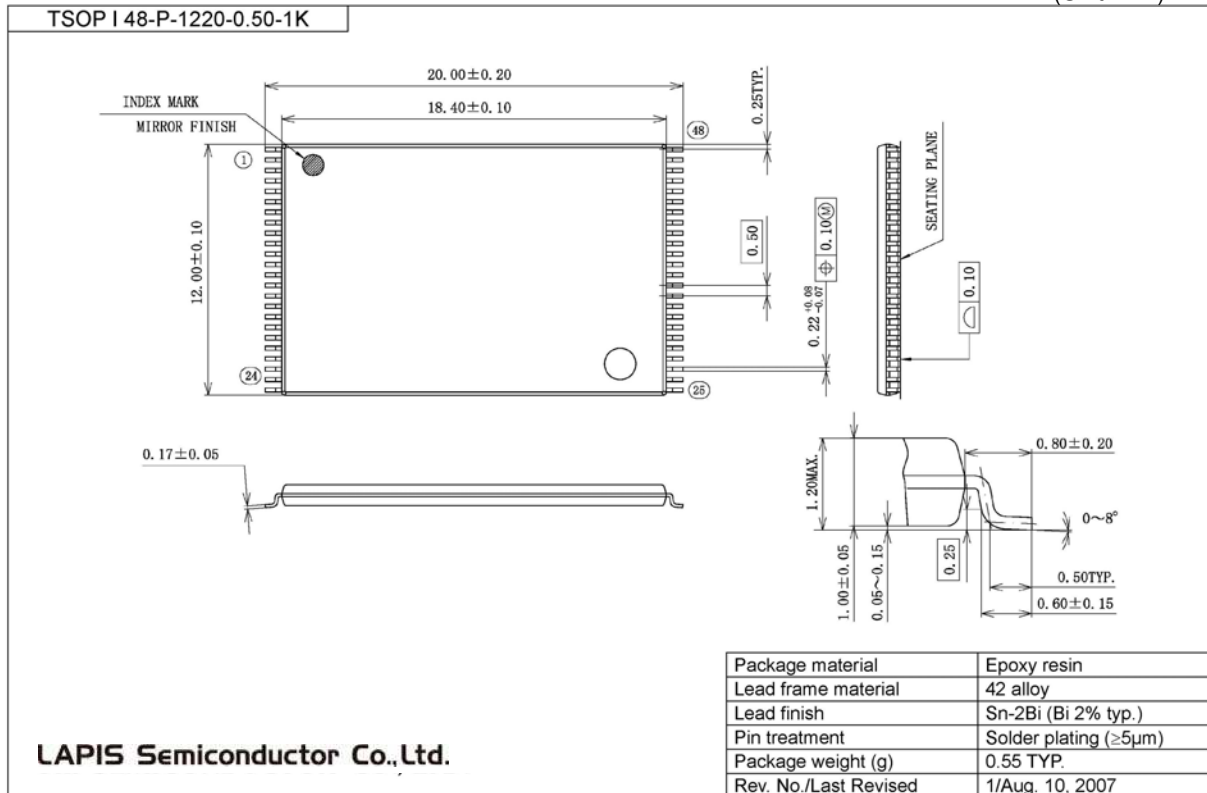


**PAGE ACCESS MODE READ CYCLE**



**PACKAGE DIMENSIONS**

(Unit: mm)



**Notes for Mounting the Surface Mount Type Package**

The surface mount type packages are very susceptible to heat in reflow mounting and humidity absorbed in storage.

Therefore, before you perform reflow mounting, contact LAPIS Semiconductor's responsible sales person for the product name, package name, pin number, package code and desired mounting conditions (reflow method, temperature and times).

**REVISION HISTORY**

Document No.	Date	Page		Description
		Previous Edition	Current Edition	
FEDR27V6454G-02-01	Apr., 2003	–	–	Final edition 1
FEDR27V6454G-02-02	May., 2003	1	1	Change 48TSOP(1) package code to –1K
FEDR27V6454G-02-03	Jun. 4, 2003	1,4	1,4	Change $t_{ACC}$ , $t_{PAC}$ to 100ns,30ns
FEDR27V6454G-02-04	Jul. 16, 2003	4	4	Change $t_{CHZ}$ to 20ns
FEDR27V6454G-02-05	Jul. 9, 2004	3	3	Add $P_D$ condition and $I_{OS} = 10mA$
FEDR27V6454G-002-05	Oct.1, 2008	–	–	Changed company logo and name to OKI SEMICONDUCTOR

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